

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	XIANFENG NI	06/10/2019
	QIAN FAN	06/10/2019
	WEI HE	06/10/2019
RECEIVING PARTY DATA		
Name:	SUZHOU HAN HUA SEMICONDUCTOR CO.,LTD	
Street Address:	99 JIN JI HU AVE,BLDG NW11,STE 303,SIP,SUZHOU,JIANGSU,CHINA 215123	
City:	SUZHOU	
State/Country:	CHINA	
Postal Code:	215123	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16438479	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Email:	in@bayramoglu-legal.com	
Correspondent Name:	GOKALP BAYRAMOGLU	
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Address Line 4:	HENDERSON, NEVADA 89014	
ATTORNEY DOCKET NUMBER:	GBBJX006	
NAME OF SUBMITTER:	GOKALP BAYRAMOGLU	
SIGNATURE:	/GOKALP BAYRAMOGLU/	
DATE SIGNED:	06/12/2019	
Total Attachments: 2		
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ASSIGNMENT

(1-8) *Insert Name(s) of Inventor(s)* (1) Xianfeng NI (2) Qian FAN
(3) Wei HE

For good and valuable consideration receipt of which is hereby acknowledged, the undersigned agree(s) to assign, and hereby do(es) assign, transfer and set over to:

(9) *Insert name of Assignee* (9) Suzhou Han Hua Semiconductor Co.,Ltd
(10) *Insert state of incorporation of Assignee* (10) China
(11) *Insert address of Assignee* (11) of 99 Jin Ji Hu Ave,Bldg NW11,Ste 303,SIP,Suzhou,Jiangsu,China 215123 (hereinafter designated as the Assignee) the entire worldwide right, title, interest, and patent applications and patents for every country, including divisions, reissues, continuations and all other extensions, rights and priorities in the invention known as and subject matter contained in
(12) *Insert Identification of Invention, such as Title, Case Number or Foreign Application Number* (12) Method for fabricating High-quality and high-uniformity III-nitride epi structure
(13) *Insert Date of Filing of Application* (13) Application is attached hereto.

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or division applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner for Patents and the duly constituted authorities of foreign countries to issue any and all Letters Patents resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, its successors and assigns, as Assignee of the entire right, title and interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) *The undersigned hereby grant(s)*

Gokalp Dayramoglu, Reg.No. 66385

the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date **2019.06.10**

Xian-feng Ni
Xianfeng NI

Date **2019.06.10**

Qian Fan
Qian FAN

Date **2019.06.10**

Wei He
Wei HE